



PATENT
0152-0668P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Matsuyoshi NAKAGAWA et al. Conf.:
Appl. No.: 10/722,450 Group: UNASSIGNED
Filed: November 28, 2003 Examiner: UNASSIGNED
For: THERMOPLASTIC RESIN COMPOSITION AND
MOLDINGS OF THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 26, 2004

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes: amendments to the specification, amendments to the Abstract and Remarks.